



Test Report issued under the responsibility of:



TEST REPORT IEC 60269-4 Low-voltage fuses Part 4: Supplementary requirements for fuse-links for the protection of semiconductor devices	
Report Number.....	03601-A-23CB0181-S
Date of issue.....	2024-04-15
Total number of pages	28
Name of Testing Laboratory preparing the Report	Suzhou Electrical Apparatus Science Research Institute Co., Ltd.(EETI)
Applicant's name	Zhejiang Tengen Electric Co., Ltd.
Address	Sulv Industry Zone, Liushi Town, Yueqing City, Zhejiang Province, P.R.China.
Test specification:	
Standard.....	IEC 60269-4:2009, IEC 60269-4:2009/AMD1:2012, IEC 60269-4:2009/AMD2:2016 see also IEC 60269-1:2006, IEC 60269-1:2006/AMD1:2009, IEC 60269-1:2006/AMD2:2014
Test procedure	CB Scheme
Non-standard test method	N/A
TRF template used	IECEE OD-2020-F1:2022, Ed.1.5
Test Report Form No.	IEC60269_4D
Test Report Form(s) Originator	CQC
Master TRF.....	Dated 2023-08-17
Copyright © 2023 IEC System of Conformity Assessment Schemes for Electrotechnical Equipment and Components (IECEE System). All rights reserved. This publication may be reproduced in whole or in part for non-commercial purposes as long as the IECEE is acknowledged as copyright owner and source of the material. IECEE takes no responsibility for and will not assume liability for damages resulting from the reader's interpretation of the reproduced material due to its placement and context. If this Test Report Form is used by non-IECEE members, the IECEE/IEC logo and the reference to the CB Scheme procedure shall be removed. This report is not valid as a CB Test Report unless signed by an approved IECEE Testing Laboratory and appended to a CB Test Certificate issued by an NCB in accordance with IECEE 02.	
General disclaimer: The test results presented in this report relate only to the object tested. This report shall not be reproduced, except in full, without the written approval of the Issuing NCB. The authenticity of this Test Report and its contents can be verified by contacting the NCB, responsible for this Test Report.	

Test item description	Fuse for protection of semiconductor devices	
Trademark(s).....	Tengen	
Manufacturer.....	Zhejiang Tengen Electric Co., Ltd. Sulv Industry Zone, Liushi Town, Yueqing City, Zhejiang Province, P.R.China.	
Model/Type reference	TGRS3Z-NEP	
Ratings	See Page 6	
Responsible Testing Laboratory (as applicable), testing procedure and testing location(s):		
<input checked="" type="checkbox"/> CB Testing Laboratory:	Suzhou Electrical Apparatus Science Research Institute Co., Ltd.(EETI)	
Testing location/ address	No.7 Yonghe Street, Binhe Road, New District, Suzhou, China	
Tested by (name, function, signature)	Fang Gang (Team leader)	
Approved by (name, function, signature) ..	Sun Aqin (Supervisor)	
<input type="checkbox"/> Testing procedure: CTF Stage 1:		
Testing location/ address		
Tested by (name, function, signature)		
Approved by (name, function, signature) ..		
<input type="checkbox"/> Testing procedure: CTF Stage 2:		
Testing location/ address		
Tested by (name + signature)		
Witnessed by (name, function, signature) . :		
Approved by (name, function, signature) .. :		
<input type="checkbox"/> Testing procedure: CTF Stage 3:		
<input type="checkbox"/> Testing procedure: CTF Stage 4:		
Testing location/ address		
Tested by (name, function, signature)		
Witnessed by (name, function, signature) . :		
Approved by (name, function, signature) .. :		
Supervised by (name, function, signature) :		